E·XF kenesas Electronics America Inc - UPD78F0522AGB-GAG-AX Datasheet



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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Details	
Product Status	Active
Core Processor	78K/0
Core Size	8-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I ² C, LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	45
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f0522agb-gag-ax

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

[List of Part Number]

	1	1	T	(1/6
78K0/Kx2 Microcontrollers	Package	Product type	Quality grace	Part Number
78K0/KB2	30-pin plastic SSOP (7.62 mm (300))	Conventional- specification products	Standard products	µPD78F0500MC-5A4-A, 78F0501MC-5A4-A, 78F0502MC-5A4-A, 78F0503MC-5A4-A, 78F0503DMC-5A4-A ^{№™}
			(A) grade products	μPD78F0500MC(A)-CAB-AX, 78F0501MC(A)-CAB-AX, 78F0502MC(A)-CAB-AX, 78F0502MC(A)-CAB-AX
			(A2) grade products	μPD78F0500MC(A2)-CAB-AX, 78F0501MC(A2)-CAB-AX, 78F0502MC(A2)-CAB-AX, 78F0503MC(A2)-CAB-AX
		Expanded- specification products	Standard products	µPD78F0500AMC-CAB-AX, 78F0501AMC-CAB-AX, 78F0502AMC-CAB-AX, 78F0503AMC-CAB-AX, 78F0503DAMC-CAB-AX ^{№te}
			(A) grade products	μPD78F0500AMCA-CAB-G, 78F0501AMCA-CAB-G, 78F0502AMCA-CAB-G, 78F0503AMCA-CAB-G
			(A2) grade products	μPD78F0500AMCA2-CAB-G, 78F0501AMCA2-CAB-G, 78F0502AMCA2-CAB-G, 78F0503AMCA2-CAB-G
	36-pin plastic FLGA (4x4)	Conventional- specification products	Standard products	µPD78F0500FC-AA3-A, 78F0501FC-AA3-A, 78F0502FC-AA3-A, 78F0503FC-AA3-A, 78F0503DFC-AA3-A ^{№™}
		Expanded- specification products	Standard products	µPD78F0500AFC-AA3-A, 78F0501AFC-AA3-A, 78F0502AFC-AA3-A, 78F0503AFC-AA3-A, 78F0503DAFC-AA3-A ^{№№}
78K0/KC2	38-pin plastic SSOP (7.62 mm	Expanded- specification	Standard products	µPD78F0511AMC-GAA-AX, 78F0512AMC-GAA-AX, 78F0513AMC-GAA-AX, 78F0513AMC-GAA-AX, 78F0513DAMC-GAA-AX ^{№0®}
	(300))	products	(A) grade products	μPD78F0511AMCA-GAA-G, 78F0512AMCA-GAA-G, 78F0513AMCA-GAA-G
			(A2) grade products	μPD78F0511AMCA2-GAA-G, 78F0512AMCA2-GAA-G, 78F0513AMCA2-GAA-G
	44-pin plastic LQFP (10x10)	Conventional- specification	Standard products	μPD78F0511GB-UES-A, 78F0512GB-UES-A, 78F0513GB-UES-A, 78F0513DGB-UES-A ^{Note}
		products	(A) grade products	μPD78F0511GB(A)-GAF-AX, 78F0512GB(A)-GAF-AX, 78F0513GB(A)-GAF-AX
			(A2) grade products	μPD78F0511GB(A2)-GAF-AX, 78F0512GB(A2)-GAF-AX, 78F0513GB(A2)-GAF-AX
		Expanded- specification	Standard products	µPD78F0511AGB-GAF-AX, 78F0512AGB-GAF-AX, 78F0513AGB-GAF-AX, 78F0513DAGB-GAF-AX ^{™ote}
		products	(A) grade products	µPD78F0511AGBA-GAF-G, 78F0512AGBA-GAF-G, 78F0513AGBA-GAF-G
			(A2) grade products	µPD78F0511AGBA2-GAF-G, 78F0512AGBA2-GAF-G, 78F0513AGBA2-GAF-G

Note The μPD78F0503D, 78F0503DA, 78F0513D, and 78F0513DA have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

48-pin products of the 78K0/KC2	78K0/KD2	78K0/KE2	78K0/KF2	IMS	IXS	ROM Capacity	Internal High- Speed RAM Capacity	Internal Expansion RAM Capacity
μPD78F0511, 78F0511A	μPD78F0521, 78F0521A	μPD78F0531, 78F0531A	-	04H	0CH	16 KB	768 bytes	_
μPD78F0512, 78F0512A	μPD78F0522, 78F0522A	μPD78F0532, 78F0532A	-	C6H	0CH	24 KB	1 KB	_
μPD78F0513, 78F0513A	μPD78F0523, 78F0523A	μPD78F0533, 78F0533A	-	C8H	0CH	32 KB	1 KB	_
μPD78F0514, 78F0514A	μPD78F0524, 78F0524A	μPD78F0534, 78F0534A	μPD78F0544, 78F0544A	ССН	0AH	48 KB	1 KB	1 KB
<i>µ</i> PD78F0515, 78F0515A, 78F0515D ^{Note 1} , 78F0515DA ^{Note 1}	μPD78F0525, 78F0525A	μPD78F0535, 78F0535A	μPD78F0545, 78F0545A	CFH	08H	60 KB		2 KB
_	<i>µ</i> PD78F0526, 78F0526A	<i>µ</i> PD78F0536, 78F0536A	<i>µ</i> PD78F0546, 78F0546A	CCH Note 2	04H	96 KB ^{Note 2}		4 KB
	μPD78F0527, 78F0527A, 78F0527D ^{Note 1} ,	μθD78F0537, 78F0537A, 78F0537D ^{Note 1} ,	μΡD78F0547, 78F0547A, 78F0547D ^{Note 1} ,	CCH Note 2	00H	128 KB ^{Note 2}		6 KB

Table 3-2. Set Values of Internal Memory Size Switching Register (IMS) and Internal Expansion RAM Size Switching Register (IXS) (48-pin products of the 78K0/KC2, 78K0/KD2, 78K0/KE2, and 78K0/KF2)

Notes 1. The ROM and RAM capacities of the products with the on-chip debug function can be debugged according to the debug target products. Set IMS and IXS according to the debug target products.

78F0547DA^{Note 1}

2. The μPD78F05x6 and 78F05x6A (x = 2 to 4) have internal ROMs of 96 KB, and the μPD78F05x7, 78F05x7A, 78F05x7D and 78F05x7DA (x = 2 to 4) have those of 128 KB. However, the set value of IMS of these devices is the same as those of the 48 KB product because memory banks are used. For how to set the memory banks, see 4.3 Memory Bank Select Register (BANK).

78F0527DA^{Note 1}

78F0537DA^{Note 1}



Address	Special Function Register (SFR) Name		Symbol	R/W	Manipulatable Bit Unit			After	к	Κ	К	К	к
			-,		1 Bit	8 Bits	16 Bits	Reset	в	С	D	Е	F
									2	2	2	2	2
FF00H	Port reg		P0	R/W	V	V	-	00H	V		√	V	V
FF01H	Port reg		P1	R/W	√	V	-	00H	V		√	V	V
FF02H	Port reg		P2	R/W	V	√	-	00H	V		√		V
FF03H	Port reg		P3	R/W	V	√	-	00H			√		
FF04H	Port reg		P4	R/W	V	√	-	00H	-			V	V
FF05H	Port reg		P5	R/W	√	V	-	00H	-	-	-	V	V
FF06H	Port reg		P6	R/W	V	√	-	00H			√		
FF07H	Port reg	ister 7	P7	R/W	V		-	00H	-		√		
FF08H	10-bit A	/D conversion result register	ADCR	R	-	-	\checkmark	0000H	V		1		
FF09H		8-bit A/D conversion result register	ADCRH	R	-		-	00H	V	\checkmark	V	V	V
FF0AH	Receive	buffer register 6	RXB6	R	-		-	FFH			\checkmark		
FF0BH	Transm	it buffer register 6	TXB6	R/W	-		-	FFH			\checkmark		
FF0CH	Port reg	ister 12	P12	R/W	\checkmark		-	00H			\checkmark		
FF0DH	Port reg	ister 13	P13	R/W	\checkmark		-	00H	-	Note	\checkmark		
FF0EH	Port reg	ister 14	P14	R/W	\checkmark		-	00H	-	Note	\checkmark		
FF0FH	Serial I/	O shift register 10	SIO10	R	-		-	00H			\checkmark		
FF10H	16-bit tir	mer counter 00	TM00	R	_	-	\checkmark	0000H	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
FF11H													
FF12H	16-bit tir	mer capture/compare register	CR000	R/W	_	-	\checkmark	0000H	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
FF13H	000												
FF14H	16-bit tir	mer capture/compare register	CR010	R/W	-	-	\checkmark	0000H	\checkmark	\checkmark	\checkmark		
FF15H	010												
FF16H	8-bit tim	er counter 50	TM50	R	-	\checkmark	-	00H	\checkmark	\checkmark	\checkmark		\checkmark
FF17H	8-bit tim	er compare register 50	CR50	R/W	-	\checkmark	-	00H		\checkmark	\checkmark		
FF18H	8-bit tim	er H compare register 00	CMP00	R/W	-	\checkmark	-	00H		\checkmark	\checkmark		
FF19H	8-bit tim	er H compare register 10	CMP10	R/W	-	\checkmark	-	00H		\checkmark	\checkmark		
FF1AH	8-bit tim	er H compare register 01	CMP01	R/W	-		-	00H			\checkmark		
FF1BH	8-bit tim	er H compare register 11	CMP11	R/W	-		-	00H			\checkmark		
FF1FH	8-bit tim	er counter 51	TM51	R	-		-	00H			\checkmark		
FF20H	Port mo	de register 0	PM0	R/W	\checkmark		-	FFH			\checkmark		
FF21H	Port mo	de register 1	PM1	R/W	\checkmark		-	FFH		\checkmark			
FF22H		de register 2	PM2	R/W	\checkmark		-	FFH		\checkmark			
FF23H	Port mo	de register 3	PM3	R/W	\checkmark		-	FFH			\checkmark		
FF24H	Port mode register 4		PM4	R/W	\checkmark		-	FFH	-		\checkmark		
FF25H	Port mode register 5		PM5	R/W	\checkmark	\checkmark	-	FFH	_	_	-	\checkmark	\checkmark
FF26H	Port mode register 6		PM6	R/W	\checkmark		_	FFH	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
FF27H	Port mode register 7		PM7	R/W	\checkmark			FFH	_	\checkmark	\checkmark	\checkmark	\checkmark
FF28H	A/D converter mode register		ADM	R/W	\checkmark	\checkmark	_	00H		\checkmark	\checkmark	\checkmark	\checkmark
FF29H	Analog i register	input channel specification	ADS	R/W	\checkmark	\checkmark	-	00H	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
FF2CH	Port mo	de register 12	PM12	R/W	\checkmark		-	FFH		\checkmark	\checkmark		\checkmark
FF2EH	Port mo	de register 14	PM14	R/W	\checkmark		-	FFH	_	Note	\checkmark		\checkmark
FF2FH		t configuration register	ADPC	R/W	\checkmark		_	00H			\checkmark		

Table 3-8.	Special Function Register List (1/	5)
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Note This register is incorporated only in 48-pin products.



3.3 Instruction Address Addressing

An instruction address is determined by contents of the program counter (PC) and memory bank select register (BANK), and is normally incremented (+1 for each byte) automatically according to the number of bytes of an instruction to be fetched each time another instruction is executed. When a branch instruction is executed, the branch destination information is set to PC and branched by the following addressing (for details of instructions, refer to the **78K/0 Series Instructions User's Manual (U12326E)**).

3.3.1 Relative addressing

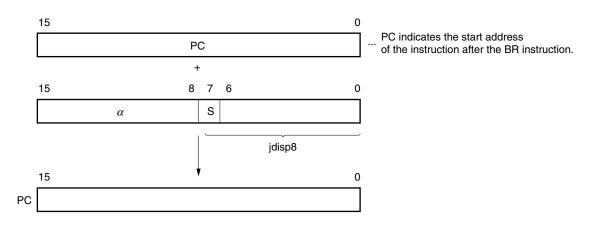
[Function]

The value obtained by adding 8-bit immediate data (displacement value: jdisp8) of an instruction code to the start address of the following instruction is transferred to the program counter (PC) and branched. The displacement value is treated as signed two's complement data (-128 to +127) and bit 7 becomes a sign bit.

In other words, relative addressing consists of relative branching from the start address of the following instruction to the –128 to +127 range.

This function is carried out when the BR \$addr16 instruction or a conditional branch instruction is executed.

[Illustration]



When S = 0, all bits of α are 0. When S = 1, all bits of α are 1.



Memory Bank Number	CPU Address	Flash Memory Real Address	Address Representation in Simulator and Debugger ^{Note 1}
Memory bank 0	08000H-0BFFFH ^{Note 2}	08000H-0BFFFH	08000H-0BFFFH
Memory bank 1		0C000H-0FFFFH	18000H-1BFFFH
Memory bank 2		10000H-13FFFH	28000H-2BFFFH
Memory bank 3		14000H-17FFFH	38000H-3BFFFH
Memory bank 4		18000H-1BFFFH	48000H-4BFFFH
Memory bank 5		1C000H-1FFFFH	58000H-5BFFFH

 Table 4-1. Memory Bank Address Representation

Notes 1. SM+ for 78K0, SM+ for 78K0/Kx2, and ID78K0-QB

2. Set the memory bank to be used by the memory bank select register (BANK) (see Figure 4-3).

For details, see the RA78K0 Ver. 3.80 Assembler Package Operation User's Manual (U17199E) and the 78K0 Microcontrollers Self Programming Library Type01 User's Manual (U18274E).

4.3 Memory Bank Select Register (BANK)

The memory bank select register (BANK) is used to select a memory bank to be used.

BANK can be set by an 8-bit memory manipulation instruction.

Reset signal generation clears BANK to 00H.

Figure 4-3. Format of Memory Bank Select Register (BANK)

Address: FFF3H After reset: 00H R/W

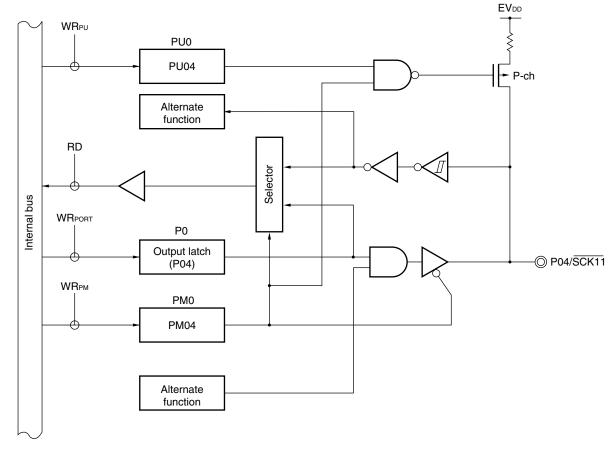
Symbol	7	6	5	4	3	2	1	0
BANK	0	0	0	0	0	BANK2	BANK1	BANK0

BANK2	BANK1	BANK0	Banks	setting		
			μPD78F05x6 and 78F05x6A	µPD78F05x7, 78F05x7A, 78F05x7D, and 78F05x7DA		
0	0	0	Common area (32 KB) + memo	ry bank 0 (16 KB)		
0	0	1	Common area (32 KB) + memo	ry bank 1 (16 KB)		
0	1	0	Common area (32 KB) + memory bank 2 (16 KB)			
0	1	1	Common area (32 KB) + memo	ry bank 3 (16 KB)		
1	0	0	Setting prohibited	Common area (32 KB) + memory bank 4 (16 KB)		
1	0	1		Common area (32 KB) + memory bank 5 (16 KB)		
0	Other than above		Setting prohibited			

Caution Be sure to change the value of the BANK register in the common area (0000H to 7FFFH). If the value of the BANK register is changed in the bank area (8000H to BFFFH), an inadvertent program loop occurs in the CPU. Therefore, never change the value of the BANK register in the bank area.

Remark x = 2 to 4

Figure 5-5. Block Diagram of P04 (2/2)



(2) 78K0/KE2 products whose flash memory is at least 48 KB and 78K0/KF2

P0: Port register 0

- PU0: Pull-up resistor option register 0
- PM0: Port mode register 0
- RD: Read signal
- WR××: Write signal

Remark With products not provided with an EVDD or EVSS pin, replace EVDD with VDD, or replace EVSS with VSS.



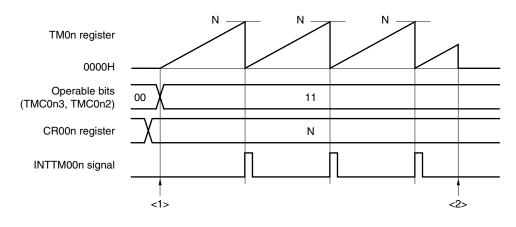
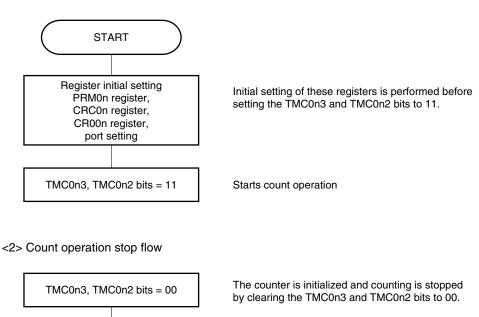


Figure 7-19. Example of Software Processing for Interval Timer Function

<1> Count operation start flow

STOP



- **Remark** n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products
 - n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

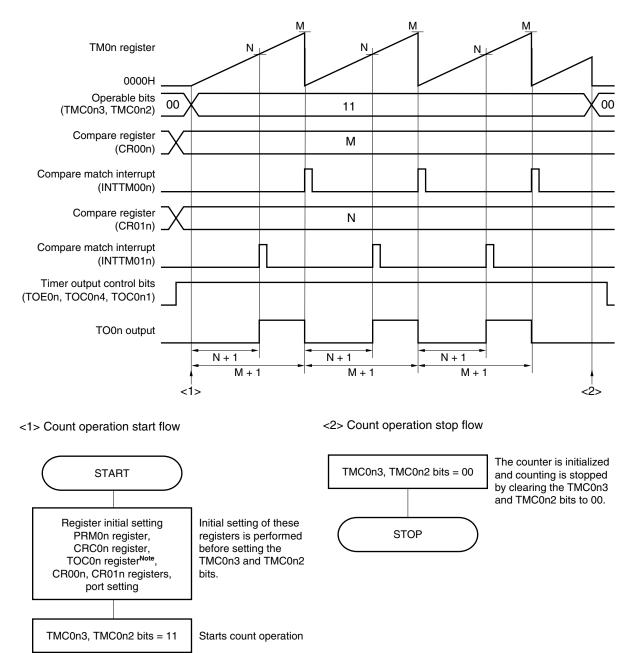


Figure 7-47. Example of Software Processing for PPG Output Operation

Note Care must be exercised when setting TOC0n. For details, see 7.3 (3) 16-bit timer output control register 0n (TOC0n).

Remarks 1. PPG pulse cycle = $(M + 1) \times Count clock cycle$

PPG duty = (N + 1)/(M + 1)

- n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products
 - n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

- Notes 2. If the peripheral hardware clock (fPRs) operates on the internal high-speed oscillation clock (fRH) (XSEL = 0), when $1.8 \text{ V} \le \text{V}_{\text{DD}} < 2.7 \text{ V}$, the setting of CKS12 = CKS11 = CKS10 = 0 (count clock: fPRs) is prohibited.
 - 3. This is settable only if 4.0 V \leq V_{DD} \leq 5.5 V.
- Cautions 1. When TMHE1 = 1, setting the other bits of TMHMD1 is prohibited. However, TMHMD1 can be refreshed (the same value is written).
 - In the PWM output mode and carrier generator mode, be sure to set the 8-bit timer H compare register 11 (CMP11) when starting the timer count operation (TMHE1 = 1) after the timer count operation was stopped (TMHE1 = 0) (be sure to set again even if setting the same value to CMP11).
 - 3. When the carrier generator mode is used, set so that the count clock frequency of TMH1 becomes more than 6 times the count clock frequency of TM51.
 - 4. The actual TOH1/INTP5/P16 pin output is determined depending on PM16 and P16, besides TOH1 output.

Remarks 1. fprs: Peripheral hardware clock frequency

Address: FF6DH After reset: 00H

2. fr.L: Internal low-speed oscillation clock frequency

(2) 8-bit timer H carrier control register 1 (TMCYC1)

This register controls the remote control output and carrier pulse output status of 8-bit timer H1. This register can be set by a 1-bit or 8-bit memory manipulation instruction. Reset signal generation clears this register to 00H.

Figure 9-7. Format of 8-Bit Timer H Carrier Control Register 1 (TMCYC1)

R/W^{Note}

	7	6	5	4	3	2	1	<0>
TMCYC1	0	0	0	0	0	RMC1	NRZB1	NRZ1

RMC1	NRZB1	Remote control output
0	0	Low-level output
0	1	High-level output at rising edge of INTTM51 signal input
1	0	Low-level output
1	1	Carrier pulse output at rising edge of INTTM51 signal input

NRZ1	Carrier pulse output status flag
0	Carrier output disabled status (low-level status)
1	Carrier output enabled status (RMC1 = 1: Carrier pulse output, RMC1 = 0: High-level status)

Note Bit 0 is read-only.

Caution Do not rewrite RMC1 when TMHE = 1. However, TMCYC1 can be refreshed (the same value is written).



Caution Do not change the count clock and interval time (by setting bits 4 to 7 (WTM4 to WTM7) of WTM) during watch timer operation.

Remarks 1. fw: Watch timer clock frequency (fPRs/2⁷ or fsub)

- 2. fprs: Peripheral hardware clock frequency
- 3. fsub: Subsystem clock frequency



15.2 Configuration of Serial Interface UART6

Serial interface UART6 includes the following hardware.

Item	Configuration
Registers	Receive buffer register 6 (RXB6)
	Receive shift register 6 (RXS6)
	Transmit buffer register 6 (TXB6)
	Transmit shift register 6 (TXS6)
Control registers	Asynchronous serial interface operation mode register 6 (ASIM6)
	Asynchronous serial interface reception error status register 6 (ASIS6)
	Asynchronous serial interface transmission status register 6 (ASIF6)
	Clock selection register 6 (CKSR6)
	Baud rate generator control register 6 (BRGC6)
	Asynchronous serial interface control register 6 (ASICL6)
	Input switch control register (ISC)
	Port mode register 1 (PM1)
	Port register 1 (P1)

Table 15-1. Configuration of Serial Interface UART6



16.2 Configuration of Serial Interfaces CSI10 and CSI11

Serial interfaces CSI10 and CSI11 include the following hardware.

Item	Configuration				
Controller	Transmit controller Clock start/stop controller & clock phase controller				
Registers	Transmit buffer register 1n (SOTB1n) Serial I/O shift register 1n (SIO1n)				
Control registers	Serial operation mode register 1n (CSIM1n) Serial clock selection register 1n (CSIC1n) Port mode register 0 (PM0) or port mode register 1 (PM1) Port register 0 (P0) or port register 1 (P1)				

Table 16-1. Configuration of Serial Interfaces CSI10 and CSI11

Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products

n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

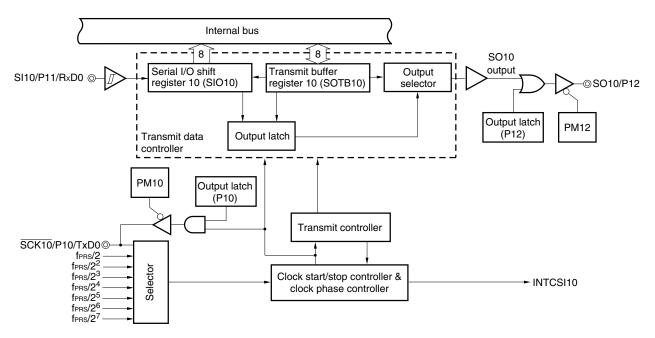
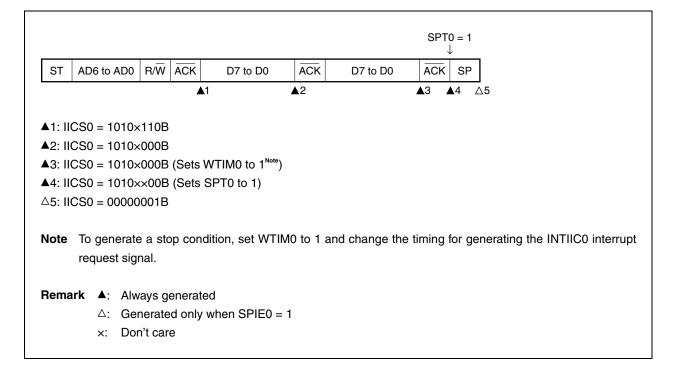


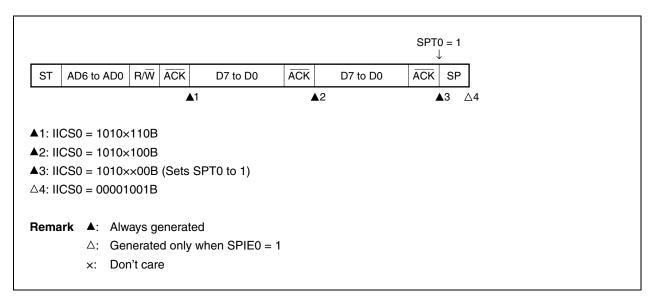
Figure 16-1. Block Diagram of Serial Interface CSI10

(c) Start ~ Code ~ Data ~ Data ~ Stop (extension code transmission)

(i) When WTIM0 = 0



(ii) When WTIM0 = 1





Address: FFA4H After reset: 05H R/W								
Symbol	7	6	5	4	3	2	1	0
OSTS	0	0	0	0	0	OSTS2	OSTS1	OSTS0
	OSTS2	OSTS1	OSTS0		Oscillation	n stabilization tin	ne selection	
						fx = 10 MHz	fx =	20 MHz
	0	0	1	2 ¹¹ /fx	2	204.8 μs 102.4 μs		S
	0	1	0	2 ¹³ /fx	8	819.2 μs 409.6 μs		S
	0	1	1	2 ¹⁴ /fx 1.64 ms 819.2 μs		S		
	1	0	0	2 ¹⁵ /fx	3	3.27 ms 1.64 ms		6
	1	0	1	2 ¹⁶ /fx	6	.55 ms	3.27 m	6
	Other than above			Setting proh	ibited			

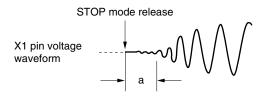
Figure 22-2. Format of Oscillation Stabilization Time Select Register (OSTS)

Cautions 1. To set the STOP mode when the X1 clock is used as the CPU clock, set OSTS before executing the STOP instruction.

- 2. Do not change the value of the OSTS register during the X1 clock oscillation stabilization time.
- 3. The oscillation stabilization time counter counts up to the oscillation stabilization time set by OSTS. If the STOP mode is entered and then released while the internal high-speed oscillation clock is being used as the CPU clock, set the oscillation stabilization time as follows.
 - Desired OSTC oscillation stabilization time ≤ Oscillation stabilization time set by OSTS

Note, therefore, that only the status up to the oscillation stabilization time set by OSTS is set to OSTC after STOP mode is released.

4. The X1 clock oscillation stabilization wait time does not include the time until clock oscillation starts ("a" below).



Remark fx: X1 clock oscillation frequency

22.2 Standby Function Operation

22.2.1 HALT mode

(1) HALT mode

The HALT mode is set by executing the HALT instruction. HALT mode can be set regardless of whether the CPU clock before the setting was the high-speed system clock, internal high-speed oscillation clock, or subsystem clock^{Note}. The operating statuses in the HALT mode are shown below.

Note The 78K0/KB2 is not provided with a subsystem clock.

- Cautions 1. To use the peripheral hardware that stops operation in the STOP mode, and the peripheral hardware for which the clock that stops oscillating in the STOP mode after the STOP mode is released, restart the peripheral hardware.
 - 2. Even if "internal low-speed oscillator can be stopped by software" is selected by the option byte, the internal low-speed oscillation clock continues in the STOP mode in the status before the STOP mode is set. To stop the internal low-speed oscillator's oscillation in the STOP mode, stop it by software and then execute the STOP instruction.
 - 3. To shorten oscillation stabilization time after the STOP mode is released when the CPU operates with the high-speed system clock (X1 oscillation), switch the CPU clock to the internal high-speed oscillation clock before the execution of the STOP instruction using the following procedure.

<1> Set RSTOP to 0 (starting oscillation of the internal high-speed oscillator) \rightarrow <2> Set MCM0 to 0 (switching the CPU from X1 oscillation to internal high-speed oscillation) \rightarrow <3> Check that MCS is 0 (checking the CPU clock) \rightarrow <4> Check that RSTS is 1 (checking internal high-speed oscillation operation) \rightarrow <5> Execute the STOP instruction

Before changing the CPU clock from the internal high-speed oscillation clock to the high-speed system clock (X1 oscillation) after the STOP mode is released, check the oscillation stabilization time with the oscillation stabilization time counter status register (OSTC).

- 4. If the STOP instruction is executed when AMPH = 1, supply of the CPU clock is stopped for 4.06 to 16.12 μ s after the STOP mode is released when the internal high-speed oscillation clock is selected as the CPU clock, or for the duration of 160 external clocks when the high-speed system clock (external clock input) is selected as the CPU clock.
- 5. Execute the STOP instruction after having confirmed that the internal high-speed oscillator is operating stably (RSTS = 1).



(2) STOP mode release

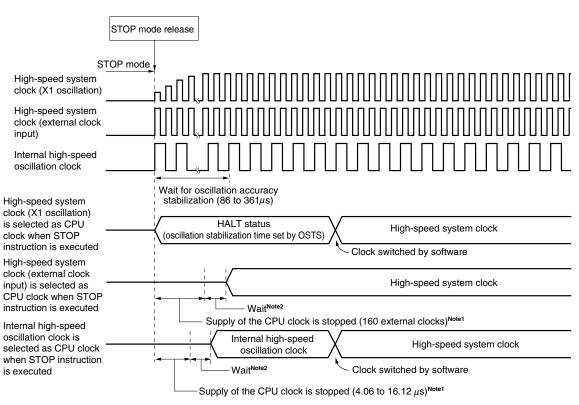


Figure 22-5. Operation Timing When STOP Mode Is Released (When Unmasked Interrupt Request Is Generated)

Notes 1. When AMPH = 1

2. The wait time is as follows:

- When vectored interrupt servicing is carried out:
 17 or 18 clocks
- When vectored interrupt servicing is not carried out: 11 or 12 clocks

The STOP mode can be released by the following two sources.

(a) Release by unmasked interrupt request

When an unmasked interrupt request is generated, the STOP mode is released. After the oscillation stabilization time has elapsed, if interrupt acknowledgment is enabled, vectored interrupt servicing is carried out. If interrupt acknowledgment is disabled, the next address instruction is executed.



Flash Memory Programming Characteristics

$(T_{A} = -40 \text{ to } +85^{\circ}\text{C}, 2.7 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, \text{ AV}_{REF} \le \text{V}_{DD}, \text{ V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

Basic characteristics

Parar	Parameter Symbol Conditions			MIN.	TYP.	MAX.	Unit			
VDD supply current IDD fxP =		fxp = 10 N	_{XP} = 10 MHz (TYP.), 20 MHz (MAX.)				4.5	11.0	mA	
Erase time	All block	Teraca						20	200	ms
Notes 1, 2	Block unit	Terasa						20	200	ms
Write time units) ^{№ote 1}	(in 8-bit	Twrwa						10	100	μs
Number of per chip	rewrites	Cerwr	1 erase + 1 write after erase = 1 rewrite Note 3	Expanded- specification Products (µPD78F05xxA (A))	 When a flash memory programmer is used, and the libraries^{Note 4} provided by Renesas Electronics are used For program update 	Retention: 15 years	1000			Times
					 When the EEPROM emulation libraries^{Note 5} provided by Renesas Electronics are used The rewritable ROM size: 4 KB For data update 	Retention: 5 years	10000			Times
				Expanded- specification Products (µPD78F05xxA (A)) Conventional- specification	Conditions other than the above ^{Note 6}	Retention: 10 years	100			Times
				Products (µPD78F05xx (A))						

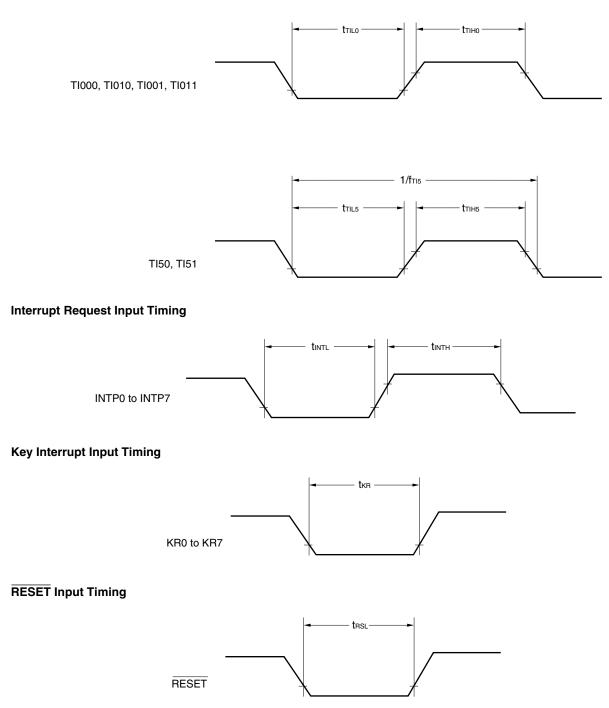
Notes 1. Characteristic of the flash memory. For the characteristic when a dedicated flash programmer, PG-FP4 or PG-FP5, is used and the rewrite time during self programming, see **Tables 27-12** to **27-14**.

- 2. The prewrite time before erasure and the erase verify time (writeback time) are not included.
- **3.** When a product is first written after shipment, "erase \rightarrow write" and "write only" are both taken as one rewrite.
- The sample library specified by the 78K0/Kx2 Flash Memory Self Programming User's Manual (Document No.: U17516E) is excluded.
- The sample program specified by the 78K0/Kx2 EEPROM Emulation Application Note (Document No.: U17517E) is excluded.
- 6. These include when the sample library specified by the 78K0/Kx2 Flash Memory Self Programming User's Manual (Document No.: U17516E) and the sample program specified by the 78K0/Kx2 EEPROM Emulation Application Note (Document No.: U17517E) are used.

Remarks 1. fxp: Main system clock oscillation frequency

2. For serial write operation characteristics, refer to 78K0/Kx2 Flash Memory Programming (Programmer) Application Note (Document No.: U17739E).

TI Timing





Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
SCKA0 cycle time	tkcy3 $4.0 \text{ V} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}$		5 V	600			ns
		$2.7 \text{ V} \leq \text{V}_{\text{DD}} < 4.0 \text{ V}$		1200			ns
SCKA0 high-/low-level width	tкнз, tк∟з	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$		tксүз/2 – 50			ns
		$2.7 \text{ V} \leq \text{V}_{\text{DD}} < 4.$	0 V	tксүз/2 – 100			ns
SIA0 setup time (to $\overline{\text{SCKA0}}$)	tsik3			100			ns
SIA0 hold time (from $\overline{\text{SCKA0}}\uparrow$)	tหรเง			300			ns
Delay time from $\overline{SCKA0}\downarrow$ to	tкsoз	$C = 100 \text{ pF}^{Note}$	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			200	ns
SOA0 output			$2.7~V \leq V_{\text{DD}} < 4.0~V$			300	ns
Time from $\overline{\text{SCKA0}}^{\uparrow}$ to STB0^{\uparrow}	tsbd			tксүз/2 – 100			ns
Strobe signal high-level width	tsвw	$\begin{array}{l} 4.0 \ V \leq V_{DD} \leq 5.5 \ V \\ \\ 2.7 \ V \leq V_{DD} < 4.0 \ V \end{array}$		tксүз – 30			ns
				tксүз – 60			ns
Busy signal setup time (to busy signal detection timing)	tвys			100			ns
Busy signal hold time (from busy signal detection timing)	tвүн			100			ns
Time from busy inactive to $\overline{SCKA0}\downarrow$	tsps	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$				2tксүз + 100	ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.$	0 V			2tксүз – 150	ns

(f) CSIA0 (master mode, SCKA0...internal clock output)

Note C is the load capacitance of the $\overline{SCKA0}$ and SOA0 output lines.



2.7 V POC Circuit Characteristics (T_A = -40 to +110°C, Vss = EVss = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage on application of supply	VDDPOC	POCMODE (option bye) = 1	2.50	2.70	2.90	V
voltage						

Remark The operations of the POC circuit are as described below, depending on the POCMODE (option byte) setting.

Option Byte Setting	POC Mode	Operation
POCMODE = 0	1.59 V mode operation	A reset state is retained until V _{POC} = 1.59 V (TYP.) is reached after the power is turned on, and the reset is released when V _{POC} is exceeded. After that, POC detection is performed at V _{POC} , similarly as when the power was turned on. The power supply voltage must be raised at a time of t _{PUP1} or t _{PUP2} when POCMODE is 0.
POCMODE = 1	2.7 V/1.59 V mode operation	A reset state is retained until VDDPOC = 2.7 V (TYP.) is reached after the power is turned on, and the reset is released when VDDPOC is exceeded. After that, POC detection is performed at VPOC = 1.59 V (TYP.) and not at VDDPOC. The use of the 2.7 V/1.59 V POC mode is recommended when the rise of the voltage, after the power is turned on and until the voltage reaches 1.8 V, is more relaxed than tPTH.

